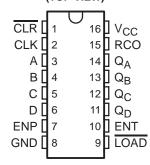
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- 2-V to 5.5-V V<sub>CC</sub> Operation
- Max t<sub>pd</sub> of 9.5 ns at 5 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  >2.3 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

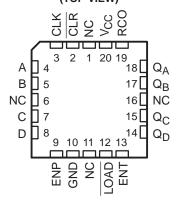
### description/ordering information

The 'LV161A devices are 4-bit synchronous binary counters designed for 2-V to 5.5-V  $V_{\rm CC}$  operation.

#### SN54LV161A . . . J OR W PACKAGE SN74LV161A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



# SN54LV161A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### ORDERING INFORMATION

TA	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0010 D	Tube of 40	SN74LV161AD	11/404 A
	SOIC – D	Reel of 2500	SN74LV161ADR	LV161A
	SOP – NS	Reel of 2000	SN74LV161ANSR	74LV161A
4000 to 0500	SSOP – DB	Reel of 2000	SN74LV161ADBR	LV161A
-40°C to 85°C		Tube of 90	SN74LV161APW	
	TSSOP - PW	Reel of 2000	SN74LV161APWR	LV161A
		Reel of 250	SN74LV161APWT	
	TVSOP - DGV	Reel of 2000	SN74LV161ADGVR	LV161A
	CDIP – J	Tube of 25	SNJ54LV161AJ	SNJ54LV161AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV161AW	SNJ54LV161AW
	LCCC – FK	Tube of 55	SNJ54LV161AFK	SNJ54LV161AFK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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### description/ordering information (continued)

These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that normally are associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function for the 'LV161A devices is asynchronous. A low level at the clear (CLR) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, load (LOAD), or enable inputs.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are ENP, ENT, and a ripple-carry output (RCO). Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with  $Q_A$  high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or  $\overline{\text{LOAD}}$ ) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

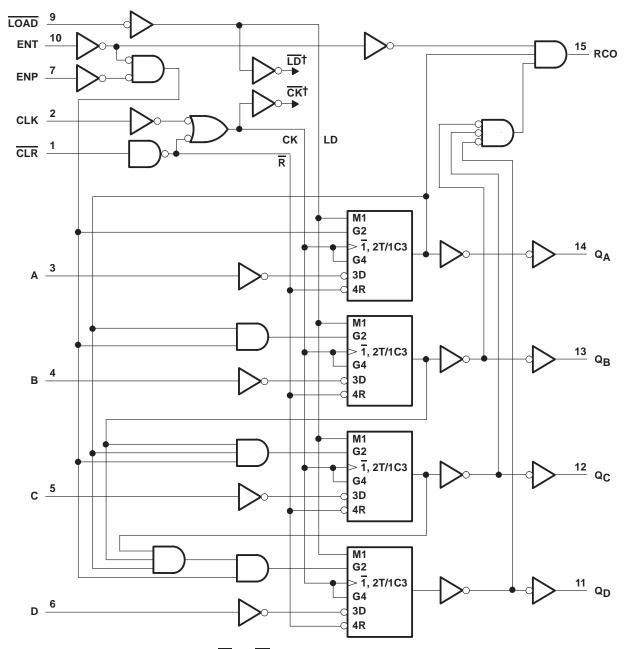
These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

#### **FUNCTION TABLE**

	II	NPUTS				OUTI	PUTS		
CLR	LOAD	ENP	ENT	CLK	QA	QB	QC	QD	FUNCTION
L	Х	Х	Χ	Х	L	L	L	L	Reset to "0"
Н	L	X	Χ	$\uparrow$	A B C D Preset D				Preset Data
Н	Н	X	L	$\uparrow$		No Change No Cou			
Н	Н	L	Χ	$\uparrow$		No CI	nange		No Count
Н	Н	Н	Н	$\uparrow$		Cou	nt up		Count
Н	X	X	Χ	$\uparrow$		No CI	nange		No Count



## logic diagram (positive logic)

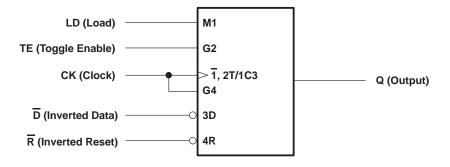


<sup>†</sup> For simplicity, routing of complementary signals  $\overline{LD}$  and  $\overline{CK}$  is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

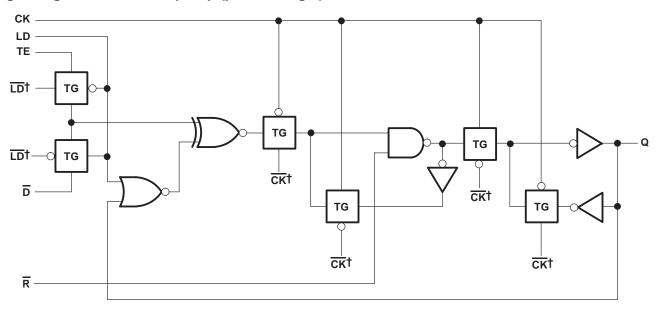
Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

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## logic symbol, each D/T flip-flop



# logic diagram, each D/T flip-flop (positive logic)

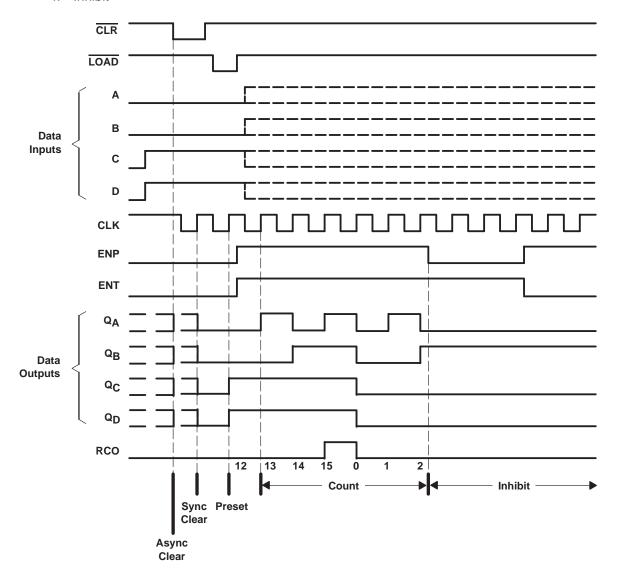


 $<sup>^{\</sup>dagger}$  The origins of  $\overline{\text{LD}}$  and  $\overline{\text{CK}}$  are shown in the overall logic diagram of the device.

## typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (asynchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)		–0.5 V to 7 V
Output voltage range applied in high or low sta	te, V <sub>O</sub> (see Notes 1 and 2)	0.5 V to V <sub>CC</sub> + 0.5 V
Voltage range applied to any output in the power	er-off state, VO (see Note 1)	–0.5 V to 7 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)		–20 mA
Output clamp current, IOK (VO < 0)		–50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )		±25 mA
Continuous current through V <sub>CC</sub> or GND		±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3)	: D package	73°C/W
	DB package	82°C/W
	DGV package	120°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T <sub>sto</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. This value is limited to 5.5 V maximum.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



## recommended operating conditions (see Note 4)

			SN54LV	161A	SN74L	/161A	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	2	5.5	V
		V <sub>CC</sub> = 2 V	1.5		1.5		
V	High level innerticate as	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V <sub>CC</sub> ×0.7		$V_{CC} \times 0.7$		V
VIH	High-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V <sub>CC</sub> = 2 V		0.5		0.5	
Mari	Low level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V	$CC \times 0.3$	V	CC×0.3	V
V <sub>IL</sub>	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	V	$CC \times 0.3$	V	CC×0.3	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		CC × 0.3	V	CC×0.3	
٧ <sub>I</sub>	Input voltage		0,0	5.5	0	5.5	V
VO	Output voltage		0	VCC	0	VCC	V
		V <sub>CC</sub> = 2 V	S. S	-50		-50	μΑ
	High lovel output output	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		-2	
ЮН	High-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		-6		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12	
		V <sub>CC</sub> = 2 V		50		50	μΑ
1	Laveland autout annuart	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6		6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0	200	0	200	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	0	100	0	100	ns/V
		V <sub>CC</sub> = 4.5 V to 5.5 V	0	20	0	20	
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN54LV161A	SN74LV161A	
PARAMETER	TEST CONDITIONS	VCC	MIN TYP MAX	MIN TYP MAX	UNIT
	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> -0.1	V <sub>CC</sub> -0.1	
.,	$I_{OH} = -2 \text{ mA}$	2.3 V	2	2	V
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48	2.48	V
	I <sub>OH</sub> = -12 mA	4.5 V	3.8	3.8	
	I <sub>OL</sub> = 50 μA	2 V to 5.5 V	0.1	0.1	
V	I <sub>OL</sub> = 2 mA	2.3 V	0.4	0.4	V
VOL	I <sub>OL</sub> = 6 mA	3 V	0.44	0.44	V
	I <sub>OL</sub> = 12 mA	4.5 V	0.55	0.55	
lį	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V	±1	±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	20	20	μΑ
l <sub>off</sub>	$V_I$ or $V_O = 0$ to 5.5 $V$	0	5	5	μΑ
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	1.8	1.8	pF

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# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

			T <sub>A</sub> = 2	25°C	SN54L	V161A	SN74L\	/161A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dulas duration	CLK high or low	7		7		7		
t <sub>W</sub>	Pulse duration	CLR low	7		7	4	7		ns
		CLR	4.5		4.5	15.11	4.5		
١.	Output the hafers OLKA	Data (A, B, C, and D)	7.5		8.5	71.	8.5		
tsu	Setup time before CLK↑	ENP, ENT	9.5		11		11		ns
		LOAD low	10		11.5		11.5		
t <sub>h</sub>	Hold time, all synchronous inputs after CLK↑		1.5		1.5		1.5		ns

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C	SN54L	V161A	SN74L\	/161A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
_	Dulas direction	CLK high or low	5		5		5		
t <sub>w</sub>	Pulse duration	CLR low	5		5	4	5		ns
		CLR	2.5		2.5	15.71	2.5		
١.	0	Data (A, B, C, and D)	5.5		6.5	71.	6.5		
tsu	Setup time before CLK↑	ENP, ENT	7.5		9		9		ns
		LOAD low	8		9.5		9.5		
t <sub>h</sub>	Hold time, all synchronous inputs after CLK↑		1		1		1		ns

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

			T <sub>A</sub> = 1	25°C	SN54L	V161A	SN74L\	/161A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dulas duration	CLK high or low	5		5		5		
t <sub>w</sub>	Pulse duration	CLR low	5		5	4	5		ns
		CLR	1.5		1.5	10,71	1.5		
١.	0	Data (A, B, C, and D)	4.5		4.5	71.	4.5		
t <sub>su</sub>	Setup time before CLK↑	ENP, ENT	5		6		6		ns
		LOAD low	5		6		6		
t <sub>h</sub>	Hold time, all synchronous inputs after CLK↑		1		1	·	1	·	ns

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

242445752	FROM	то	LOAD	T,	Δ = 25°C	;	SN54L\	/161A	SN74L	/161A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f			C <sub>L</sub> = 15 pF	50*	125*		40*		40		MHz
fmax			$C_L = 50 pF$	30	95		25		25		IVITIZ
		Q			7.9*	16.2*	1*	19.5*	1	19.5	
	CLK	RCO (count mode)			8.9*	17*	1*	20.5*	1	20.5	
<sup>t</sup> pd		RCO (preset mode)	C <sub>L</sub> = 15 pF		11.9*	20.6*	1*	24.5*	1	24.5	ns
	ENT	RCO			8.3*	15.7*	1*	19*	1	19	
		Q			8.8*	17*	1* 4	20.5*	1	20.5	
<sup>t</sup> PHL	CLR	RCO			9.8*	16.6*	1*	20*	1	20	
		Q			10.5	19.2	01	22.5	1	22.5	
	CLK	RCO (count mode)			11.7	20	1	23.5	1	23.5	
<sup>t</sup> pd		RCO (preset mode)	C <sub>L</sub> = 50 pF		14.5	23.6	1	27.5	1	27.5	ns
	ENT	RCO			11	18.7	1	22	1	22	
<b></b>	CLD	Q			11.4	20	1	23.5	1	23.5	
<sup>t</sup> PHL	CLR	RCO			12.6	19.6	1	23	1	23	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	Δ = 25°C	;	SN54L	V161A	SN74L	V161A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f			C <sub>L</sub> = 15 pF*	80*	165*		70*		70		MHz
fmax			C <sub>L</sub> = 50 pF	55	125		50		50		IVITIZ
		Q			6	12.8	1*	15*	1	15	
	CLK	RCO (count mode)			6.7	13.6	1*	16*	1	16	
<sup>t</sup> pd*		RCO (preset mode)	C <sub>L</sub> = 15 pF		8.6	17.2	1*	20*	1	20	ns
	ENT	RCO			6.2	12.3	1*	14.5*	1	14.5	
		Q			6.5	13.6	1*,4	16*	1	16	
<sup>t</sup> PHL*	CLR	RCO			7.2	13.2	1*	15.5*	1	15.5	
		Q			7.8	16.3	01	18.5	1	18.5	
	CLK	RCO (count mode)			8.7	17.1	1	19.5	1	19.5	
<sup>t</sup> pd		RCO (preset mode)	C <sub>L</sub> = 50 pF		10.6	20.7	1	23.5	1	23.5	ns
	ENT	RCO			8.3	15.8	1	18	1	18	
4	CLD	Q			8.4	17.1	1	19.5	1	19.5	
t <sub>PHL</sub>	CLR	RCO			9.2	16.7	1	19	1	19	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T,	4 = 25°C	;	SN54L\	√161A	SN74L	V161A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f			C <sub>L</sub> = 15 pF	135*	220		115*		115		MHz
fmax			C <sub>L</sub> = 50 pF	95	165		85		85		IVITIZ
		Q			4.5*	8.1*	1*	9.5*	1	9.5	
	CLK	RCO (count mode)			5.1*	8.1*	1*	9.5*	1	9.5	
<sup>t</sup> pd		RCO (preset mode)	C <sub>L</sub> = 15 pF		6.3*	10.3*	1*	12*	1	12	ns
	ENT	RCO			4.8*	8.1*	1*	9.5*	1	9.5	
		Q			4.9*	9*	1*,4	10.5*	1	10.5	
<sup>t</sup> PHL	CLR	RCO			5.5*	8.6*	1(*)	10*	1	10	
		Q			5.9	10.1	01	11.5	1	11.5	
	CLK	RCO (count mode)			6.6	10.1	1	11.5	1	11.5	
<sup>t</sup> pd		RCO (preset mode)	C <sub>L</sub> = 50 pF		7.8	12.3	1	14	1	14	ns
	ENT	RCO			6.1	10.1	1	11.5	1	11.5	
<b></b>	CLD	Q			6.3	11	1	12.5	1	12.5	
<sup>t</sup> PHL	CLR	RCO	]		6.9	10.6	1	12	1	12	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

# noise characteristics, $V_{CC} = 3.3 \text{ V}$ , $C_L = 50 \text{ pF}$ , $T_A = 25^{\circ}\text{C}$ (see Note 5)

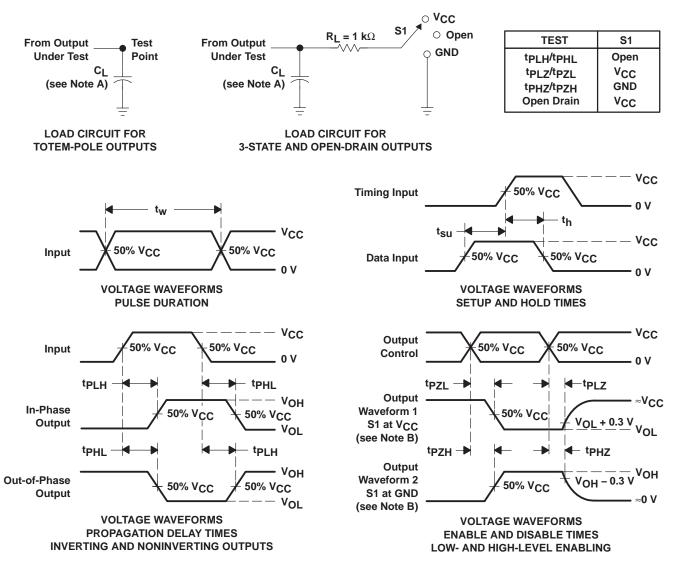
	DADAMETED	SN	Α		
	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		0.3	0.8	V
V <sub>OL</sub> (V)	Quiet output, minimum dynamic VOL		-0.2	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3		V
VIH(D)	High-level dynamic input voltage	2.31			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

# operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CO	VCC	TYP	UNIT	
<u> </u>	Down dissipation consistence	C. F0 pF	f = 10 MHz	3.3 V	23.6	٠,
Cpd	Power dissipation capacitance	$C_L = 50 pF$ ,	T = 10 MHZ	5 V	25.8	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics:  $PRR \le 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_f \le 3 \text{ ns}$ ,  $t_f \le 3 \text{ ns}$ .
- D. The outputs are measured one at a time, with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. tpz and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

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### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LV161AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161APWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161APWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV161APWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



### PACKAGE OPTION ADDENDUM

23-Apr-2007

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

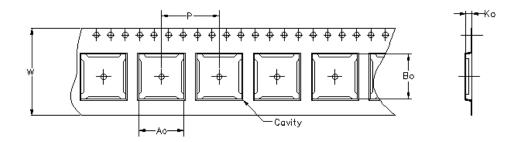
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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Carrier tape design is defined largely by the component lentgh, width, and thickness.

Ao =	Dimension	designed	to	accommodate	the	component	width.
Bo =	Dímension	designed	to	accommodate	the	component	length.
Ko =	Dímension	designed	to	accommodate	the	component	thickness.
W = Overall width of the carrier tape.							
P = Pitch between successive cavity centers.							

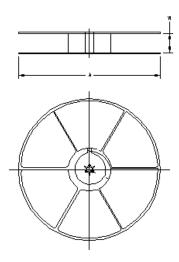


### TAPE AND REEL INFORMATION



19-May-2007

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV161ADBR	DB	16	MLA	330	16	8.2	6.6	2.5	12	16	Q1
SN74LV161ADGVR	DGV	16	MLA	330	12	6.8	4.0	1.6	8	16	Q1
SN74LV161ADR	D	16	FMX	0	16	6.5	10.3	12.1	2	16	Q1
SN74LV161ANSR	NS	16	MLA	330	16	8.2	10.5	2.5	12	16	Q1
SN74LV161APWR	PW	16	MLA	330	12	7.0	5.6	1.6	8	12	Q1



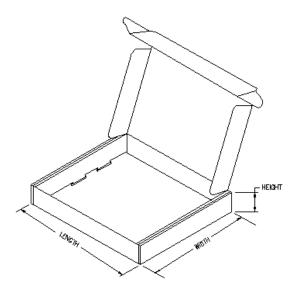
## TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LV161ADBR	DB	16	MLA	342.9	336.6	28.58
SN74LV161ADGVR	DGV	16	MLA	338.1	340.5	20.64
SN74LV161ADR	D	16	FMX	342.9	336.6	28.58
SN74LV161ANSR	NS	16	MLA	342.9	336.6	28.58
SN74LV161APWR	PW	16	MLA	338.1	340.5	20.64





19-May-2007



## DGV (R-PDSO-G\*\*)

#### **24 PINS SHOWN**

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

# D (R-PDSO-G16)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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